

Accepted Manuscript

Title: A novel technique for slicing SiC ingots by EDM utilizing a running ultra-thin foil tool electrode

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PII: S0141-6359(17)30647-5

DOI: <https://doi.org/10.1016/j.precisioneng.2017.11.012>

Reference: PRE 6693

To appear in: *Precision Engineering*

Received date: 7-11-2017

Accepted date: 9-11-2017



Please cite this article as: Zhao Yonghua, Kunieda Masanori, Abe Kohzoh. A novel technique for slicing SiC ingots by EDM utilizing a running ultra-thin foil tool electrode. *Precision Engineering* <https://doi.org/10.1016/j.precisioneng.2017.11.012>

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A novel technique for slicing SiC ingots by EDM utilizing a running ultra-thin foil tool electrode

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Highlights

- A novel running foil electrical discharge slicing process was developed.
- 1-inch SiC ingot was successfully sliced with 50 μ m thick foil tool electrode.
- Slicing kerf loss less than 100 μ m was achieved.
- Three simultaneously slicing was successfully performed by rewinding the foil tool.

ABSTRACT

Recently, a multi-wire electrical discharge slicing (EDS) process has been proposed for slicing SiC ingots into wafers. A significant reduction in kerf loss is expected with this method compared with the conventional multi-wire saw method. However, this process entails a high risk of wire breakage. Therefore, in the present study, a novel electrical discharge slicing process utilizing a running ultra-thin foil tool electrode is demonstrated for the slicing of SiC

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